

**AMENDMENTS TO THE CLAIMS:**

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

**LISTING OF CLAIMS:**

1 and 2 (Cancelled).

3. (Previously presented) A photosensitive resin composition according to claim 11, wherein said diamine is a diaminopolysiloxane.

4. (Previously presented) A photosensitive resin composition according to claim 11, wherein said transmittance is in a range of 40%-68%.

5-9. (Cancelled).

10. (Currently amended) A photosensitive resin composition which ~~comprises~~ consists essentially of (1) a polyimide precursor produced using (a) an oxydiphthalic acid or acid anhydride thereof as a reactant for forming the polyimide precursor, and (b) at least one diamine selected from the group consisting of diaminodiphenyl ether, diaminodiphenyl sulfone, metaphenylene diamine, p-phenylenediamine, p-xylylenediamine, diaminonaphthalene, dimethylbenzidine, dimethoxybenzidine, diaminodiphenylmethane, diaminodiphenylsulfide, benzophenonediamine, bis{(aminophenoxy) phenyl}sulfone, hexafluoro-bis(aminophenyl)propane, bis{(aminophenoxy)phenyl}propane, dimethyl-diaminophenyl-methane, tetramethyl-diaminodiphenylmethane, bis{(aminophenoxy)phenyl} sulfone, bis(aminophenyl)propane and

diaminopolysiloxane, (2) an addition-polymerizable compound, and (3) a photoinitiator, and which is adapted to be exposed and developed using an i-line stepper which uses monochromatic light, the polyimide precursor being such that a 20  $\mu$ m thick film thereof has a transmittance, at 365nm, of at least 40%.

11. (Original) A photosensitive resin composition according to claim 10, wherein the addition-polymerizable compound is tetraethylene glycol dimethacrylate.

12. (Original) A photosensitive resin composition according to claim 11, wherein said diamine is a diaminodiphenyl ether.

13. (Original) A photosensitive resin composition according to claim 10, wherein said diamine is a diaminodiphenyl ether.

14-16. (Cancelled).

17. (Previously presented) A photosensitive resin according to claim 13, wherein the diamine is selected from the group consisting of 4,4'-diaminodiphenyl ether, 2,4'-diaminodiphenyl ether, 3,4'-diaminodiphenyl ether and 3,3'-diaminodiphenyl ether.

18. (Cancelled).

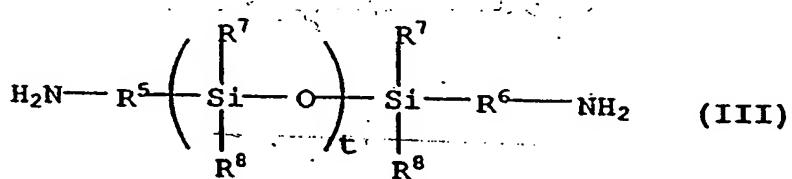
19. (Currently amended) A photosensitive resin composition according to claim 10, wherein said at least one diamine is selected from the group consisting of

4, 4'-diaminodiphenyl ether, 2, 4'-diaminodiphenyl ether, 3, 4'-diaminodiphenyl ether, 3, 3'-diaminodiphenyl ether, 4, 4'-diaminodiphenyl sulfone, 3, 3'-diaminodiphenyl sulfone and metaphenylenediamine.

20. (Previously presented) A photosensitive resin composition according to claim 19, wherein said at least one diamine is selected from the group consisting of 3, 4'-diaminodiphenyl ether, 3, 3'-diaminodiphenyl sulfone, 4, 4'-diaminodiphenyl sulfone and methaphenylenediamine.

21. (Previously presented) A photosensitive resin composition according to claim 10, wherein the at least one diamine includes a diaminopolysiloxane represented by the formula (III):

(III):



wherein R<sup>5</sup> and R<sup>6</sup> each represent a divalent hydrocarbon group; R<sup>7</sup> and R<sup>8</sup> each represent a monovalent hydrocarbon group; each of R<sup>5</sup>, R<sup>6</sup>, R<sup>7</sup> and R<sup>8</sup> may be the same or different; and t represents an integer of 1 to 5.

22. (Previously presented) A photosensitive resin composition according to claim 21, wherein said divalent hydrocarbon group has 1 to 3 carbon atoms, and said monovalent hydrocarbon group has 1 to 3 carbon atoms.

23. (Previously presented) A photosensitive resin composition which comprises (1) a polyimide precursor produced using (a) an oxydiphthalic acid or acid anhydride thereof as a reactant for forming the polyimide precursor, and (b) at least one diamine including a hydroxyl group-containing diamine, (2) an addition-polymerizable compound, and (3) a photoinitiator, and which is adapted to be exposed and developed using an i-line stepper which uses monochromatic light, the polyimide precursor being such that a 20  $\mu\text{m}$  thick film thereof has a transmittance, at 365 nm, of at least 40%.

24. (New) A photosensitive resin composition according to claim 10, wherein said polyimide precursor is a condensation product of said oxydiphthalic acid or acid anhydride thereof and said at least one diamine.

25. (New) A photosensitive resin composition according to claim 10, wherein said at least one diamine is selected from the group consisting of diaminodiphenyl sulfone, metaphenylene diamine, p-phenylenediamine, p-xylylenediamine, diaminonaphthalene, dimethylbenzidine, dimethoxylbenzidine, diaminodiphenylmethane, diaminodiphenylsulfide, benzophenonediamine, bis{(aminophenoxy) phenyl}sulfone, hexafluoro-bis(aminophenyl)propane, bis{(aminophenoxy)phenyl}propane, dimethyl-diaminophenyl-methane, tetramethyl-diaminodiphenylmethane, bis{(aminophenoxy)phenyl} sulfone, bis(aminophenyl)propane and diaminopolysiloxane.